



## STB85NF3LL

### N-CHANNEL 30V - 0.006Ω - 85A D<sup>2</sup>PAK LOW GATE CHARGE STripFET™II POWER MOSFET

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STB85NF3LL	30 V	< 0.008 Ω	85 A

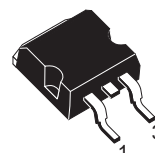
- TYPICAL R<sub>DS(on)</sub> = 0.0075Ω (@4.5V)
- OPTIMAL R<sub>DS(on)</sub> x Q<sub>g</sub> TRADE-OFF @4.5V
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED
- ADD SUFFIX "T4" FOR ORDERING IN TAPE & REEL

#### DESCRIPTION

This application specific Power MOSFET is the third generation of STMicroelectronics unique "Single Feature Size" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

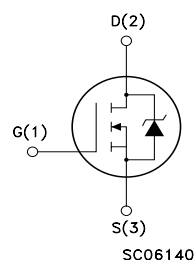
#### APPLICATIONS

- SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY CPU CORE DC/DC CONVERTERS



D<sup>2</sup>PAK

#### INTERNAL SCHEMATIC DIAGRAM



#### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	30	V
V <sub>GS</sub>	Gate- source Voltage	± 16	V
V <sub>GSM</sub>	Gate-source Voltage Pulsed (t <sub>p</sub> ≤ 50 μs; duty cycle 25%; T <sub>j</sub> ≤ 150°C)	± 20	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	85	A
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 100°C	60	A
I <sub>DM</sub> (●)	Drain Current (pulsed)	340	A
P <sub>TOT</sub>	Total Dissipation at T <sub>C</sub> = 25°C	110	W
	Derating Factor	0.73	W/°C
T <sub>stg</sub>	Storage Temperature	-65 to 175	°C
T <sub>j</sub>	Max. Operating Junction Temperature	175	°C

(●) Pulse width limited by safe operating area

## STB85NF3LL

### THERMAL DATA

Rthj-case	Thermal Resistance Junction-case Max	1.36	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5	°C/W
T <sub>I</sub>	Maximum Lead Temperature For Soldering Purpose	300	°C

### ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 µA, V <sub>GS</sub> = 0	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating, T <sub>C</sub> = 125 °C			1 10	µA µA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 16V			±100	nA

ON (1)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA	1			V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40 A V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 40 A		0.006 0.0075	0.008 0.0095	Ω Ω

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>DS(on)max</sub> , I <sub>D</sub> = 40 A		30		S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0		2210		pF
C <sub>oss</sub>	Output Capacitance			635		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			138		pF

## ELECTRICAL CHARACTERISTICS (CONTINUED)

## SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 15V, I_D = 30A$		22		ns
$t_r$	Rise Time	$R_G = 4.7\Omega, V_{GS} = 4.5V$ (see test circuit, Figure 3)		130		ns
$Q_g$	Total Gate Charge	$V_{DD} = 24V, I_D = 60A,$		30	40	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 4.5V$		9		nC
$Q_{gd}$	Gate-Drain Charge			12.5		nC

## SWITCHING OFF

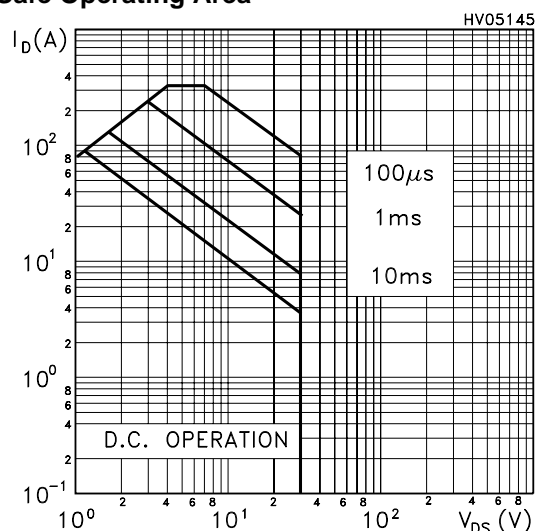
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off-Delay Time	$V_{DD} = 15V, I_D = 30A,$		36.5		ns
$t_f$	Fall Time	$R_G = 4.7\Omega, V_{GS} = 4.5V$ (see test circuit, Figure 3)		36.5		ns
$t_{d(off)}$	Off-voltage Rise Time	$V_{clamp} = 24V, I_D = 30A$		32		ns
$t_f$	Fall Time	$R_G = 4.7\Omega, V_{GS} = 4.5V$		23		ns
$t_c$	Cross-over Time	(see test circuit, Figure 5)		40		ns

## SOURCE DRAIN DIODE

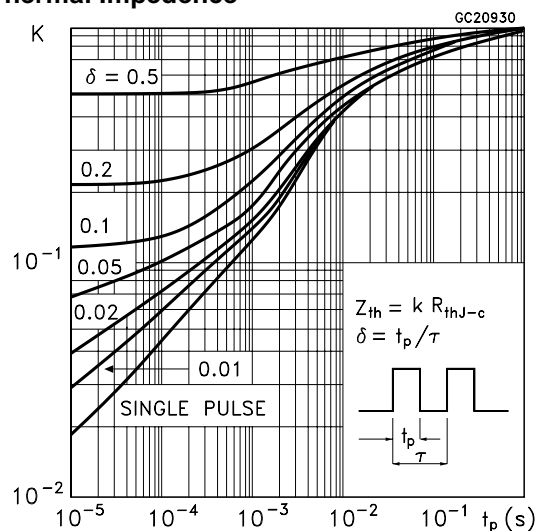
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain Current				85	A
$I_{SDM(2)}$	Source-drain Current (pulsed)				340	A
$V_{SD(1)}$	Forward On Voltage	$I_{SD} = 85A, V_{GS} = 0$			1.3	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 85A, di/dt = 100A/\mu s,$		65		ns
$Q_{rr}$	Reverse Recovery Charge	$V_{DD} = 15V, T_j = 150^\circ C$		105		nC
$I_{RRM}$	Reverse Recovery Current	(see test circuit, Figure 5)		3.4		A

Note: 1. Pulsed: Pulse duration = 300  $\mu s$ , duty cycle 1.5 %.  
2. Pulse width limited by safe operating area.

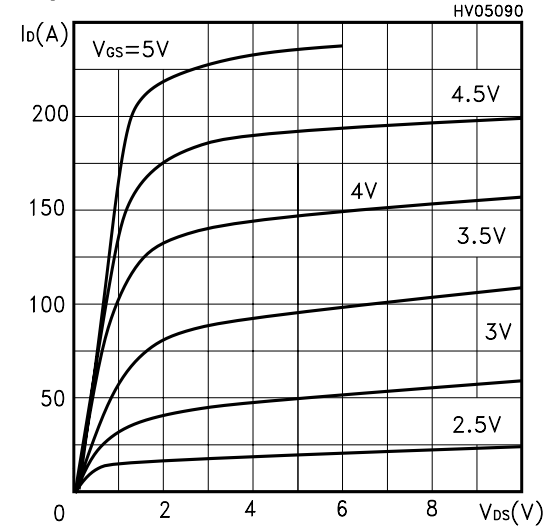
## Safe Operating Area



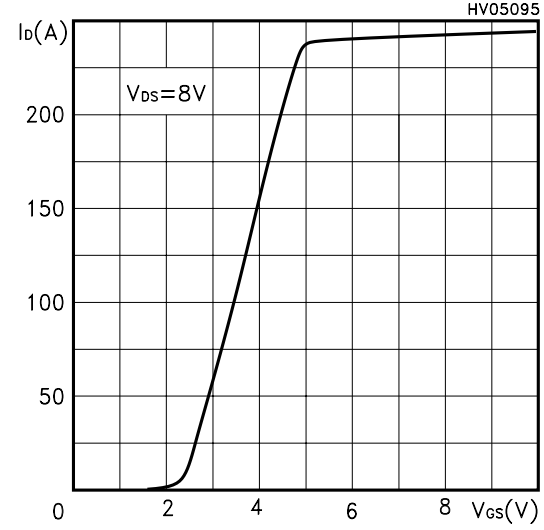
## Thermal Impedance



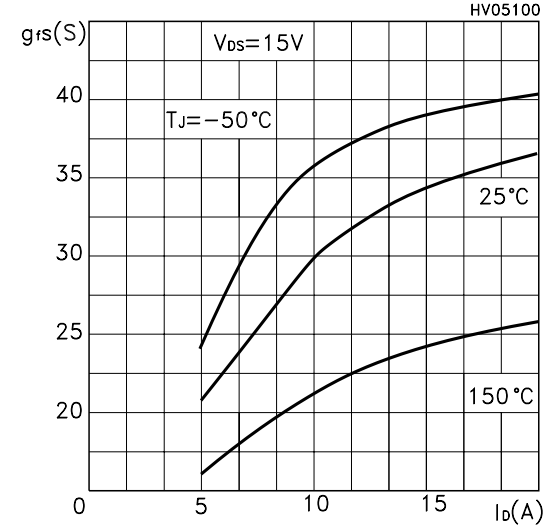
Output Characteristics



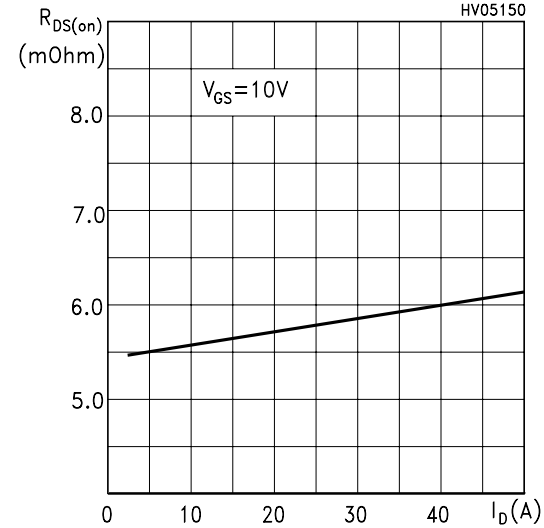
Transfer Characteristics



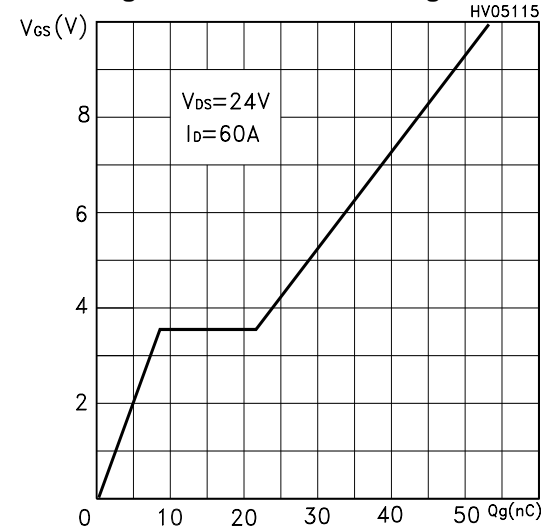
Transconductance



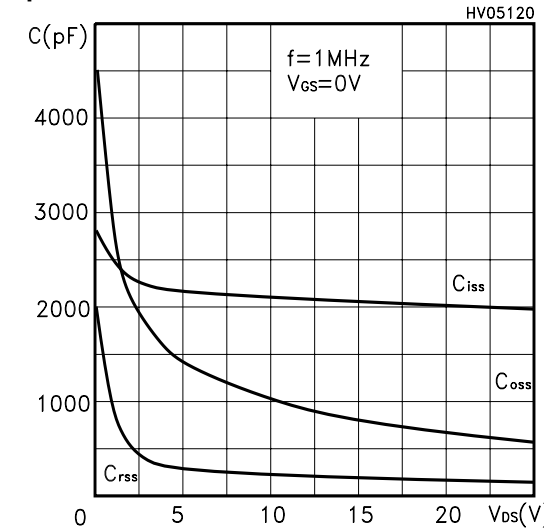
Static Drain-source On Resistance



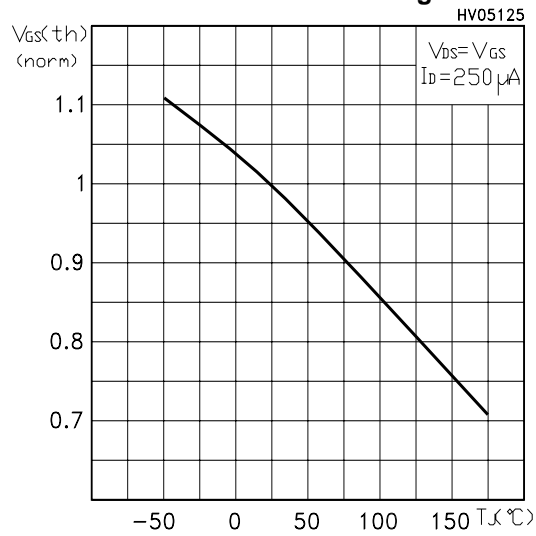
Gate Charge vs Gate-source Voltage



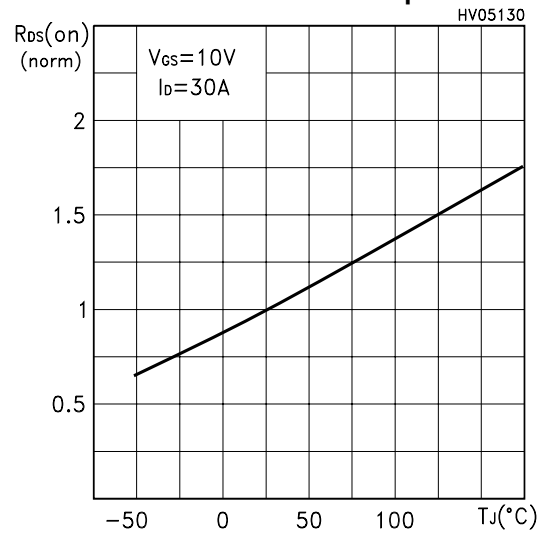
Capacitance Variations



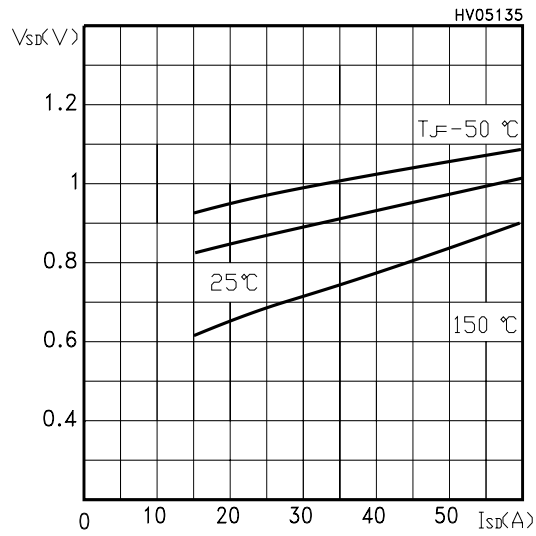
Normalized Gate Threshold Voltage vs Temp.



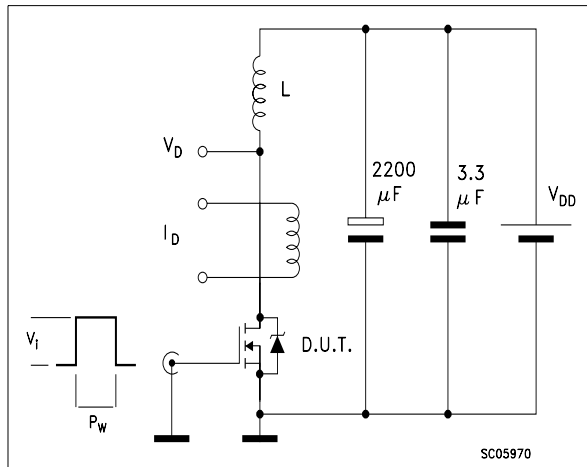
Normalized On Resistance vs Temperature



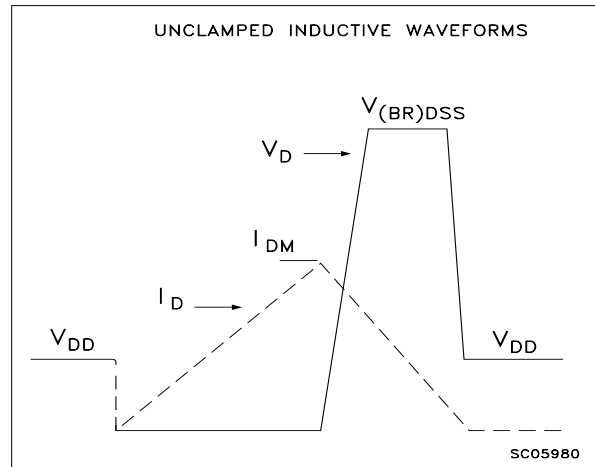
Source-drain Diode Forward Characteristics



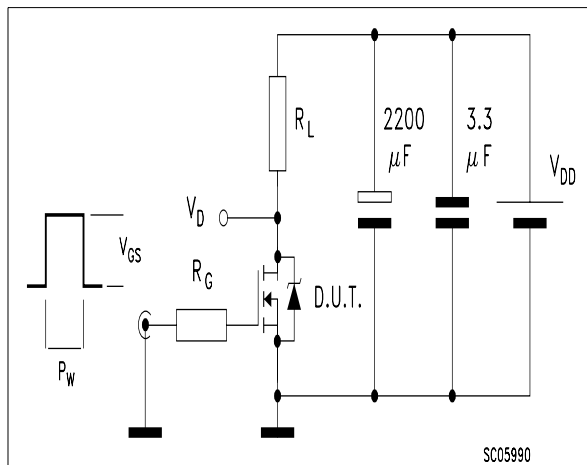
**Fig. 1: Unclamped Inductive Load Test Circuit**



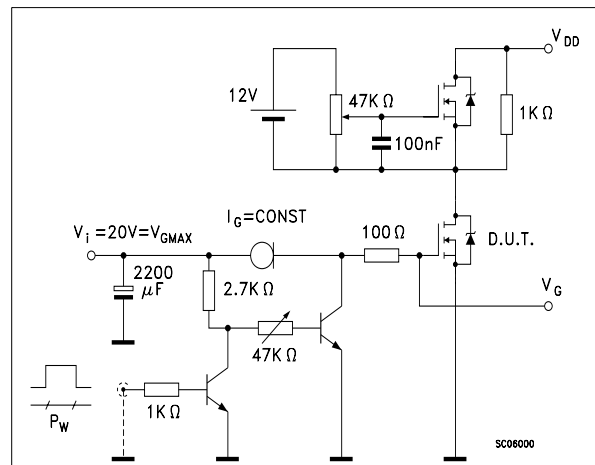
**Fig. 2: Unclamped Inductive Waveform**



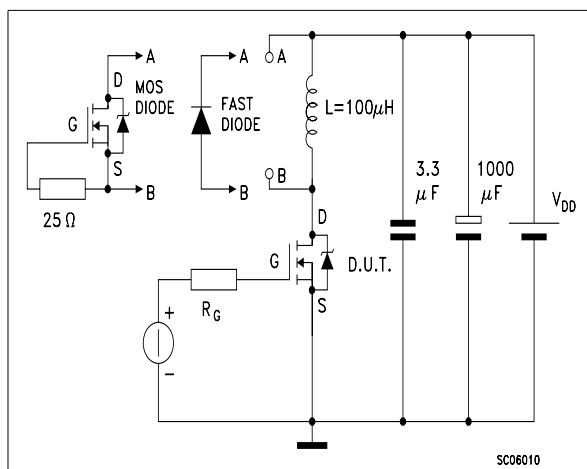
**Fig. 3: Switching Times Test Circuit For Resistive Load**



**Fig. 4: Gate Charge test Circuit**

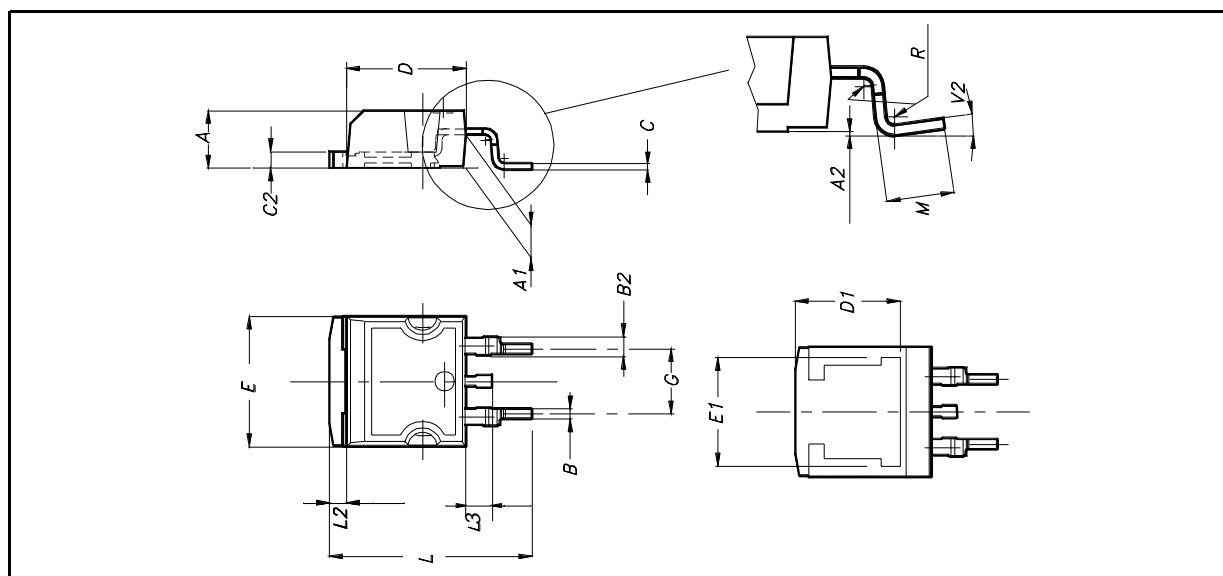


**Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times**

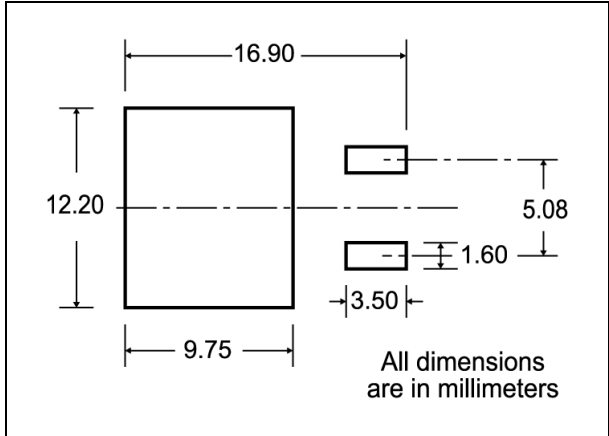


## D<sup>2</sup>PAK MECHANICAL DATA

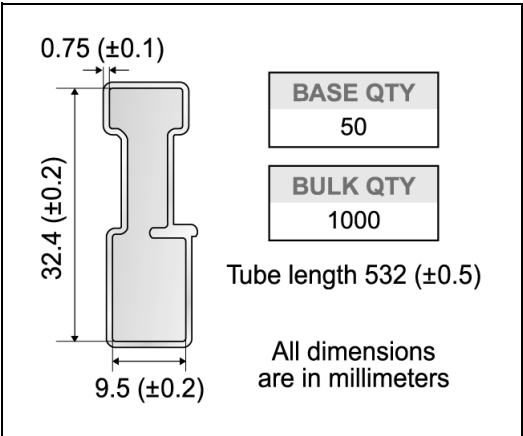
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		8°			



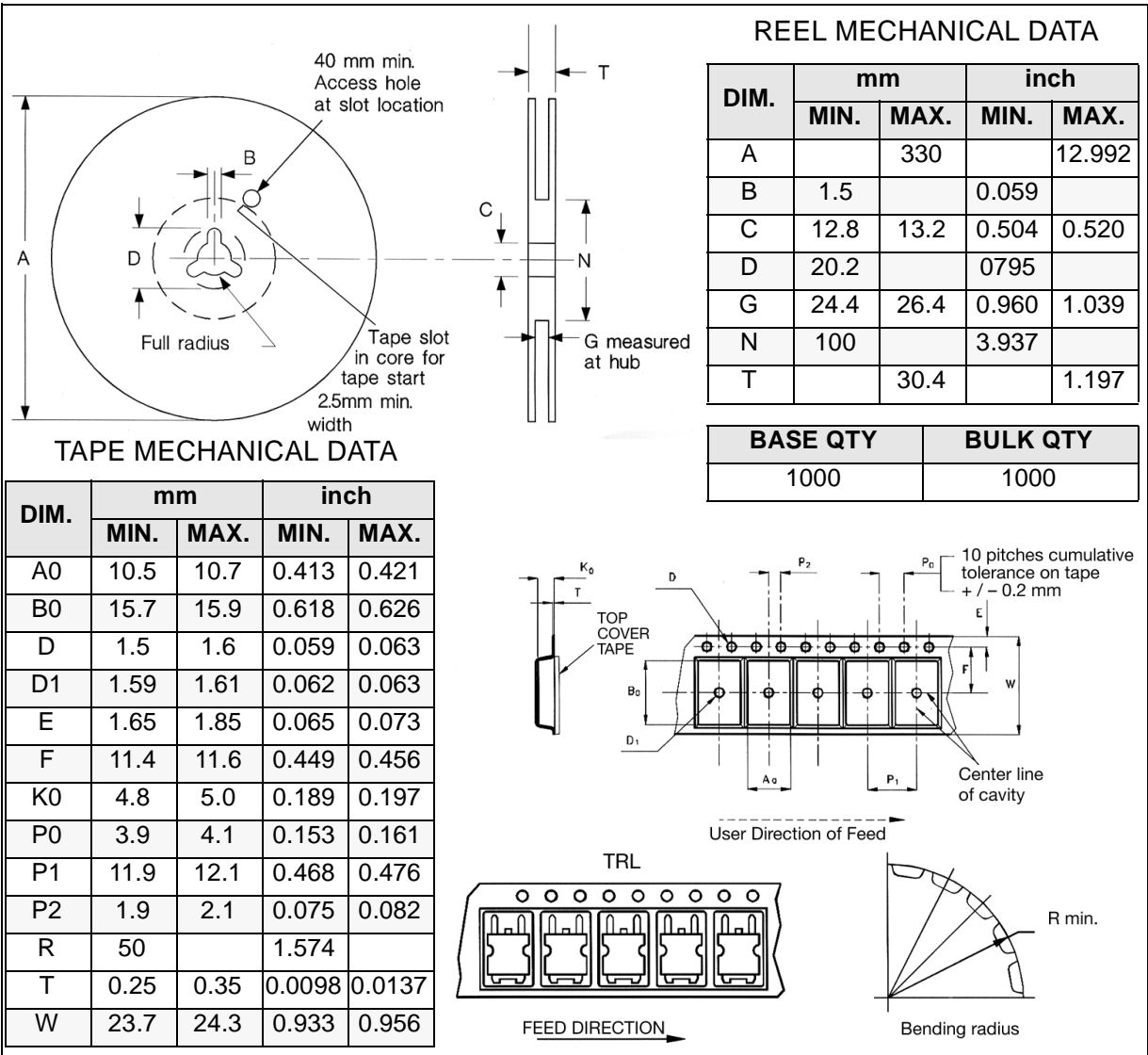
D<sup>2</sup>PAK FOOTPRINT



TUBE SHIPMENT (no suffix)\*



TAPE AND REEL SHIPMENT (suffix "T4")\*



\* on sales type  
8/9



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